

## CY7C131E, CY7C131AE CY7C136E, CY7C136AE

# 1 K / 2 K × 8 Dual-port Static RAM

### Features

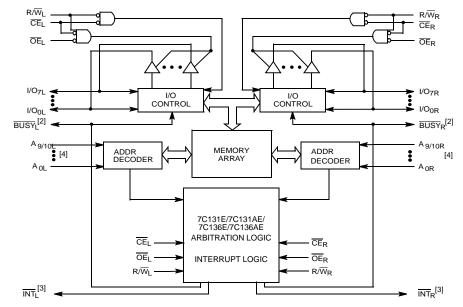
- True dual-ported memory cells, which allow simultaneous reads of the same memory location
- 1 K / 2 K × 8 organization
- 0.35 micron complementary metal oxide semiconductor (CMOS) for optimum speed and power
- High speed access: 15 ns
- Low operating power: I<sub>CC</sub> = 110 mA (typical), Standby: I<sub>SB3</sub> = 0.05 mA (typical)
- Fully asynchronous operation
- Automatic power-down
- BUSY output flag to indicate access to the same location by both ports
- INT flag for port-to-port communication
- Available in 52-pin plastic leaded chip carrier (PLCC), 52-pin plastic quad flat package (PQFP)
- Pb-free packages available

### **Functional Description**

CY7C131E / CY7C131AE / CY7C136E / CY7C136AE are high-speed, low-power CMOS 1 K / 2 K × 8 dual-port static RAMs. Two ports are provided permitting independent access to any location in memory. The CY7C131E / CY7C131AE / CY7C136E/CY7C136AE can be used as a standalone dual-port static RAM. It is the solution to applications requiring shared or buffered data, such as cache memory for DSP, bit-slice, or multiprocessor designs.

Each port <u>has</u> independent control <u>pins</u>; chip enable ( $\overline{CE}$ ), write enable ( $\overline{R/W}$ ), <u>and</u> output enable (<u>OE</u>). Two flags are provided on each port, BUSY and INT. The BUSY flag signals that the port is trying to access the same location, which is currently being accessed by the other port. The INT is an interrupt flag indicating that data is placed in a unique location<sup>[1]</sup>. The BUSY and INT flags are push pull outputs. An automatic power-down feature is controlled independently on each port by the chip enable ( $\overline{CE}$ ) pins.

The CY7C131E / CY7C131AE / CY7C136E / CY7C136AE are available in 52-pin Pb-free PLCC and 52-pin Pb-free PQFP.



#### Notes

- 1. Unique location used by interrupt flag: 1 K x 8: Left port reads from 3FE, Right port reads from 3FF; 2 K x 8: Left port reads from 7FE. Right port reads from 7FF.
- 2. BUSY is a push-pull output. No pull-up resistor required.
- 3. INT: push-pull output. No pull-up resistor required.
- 4. 1 K × 8: A0–A9, 2 K × 8: A0–A10, address lines are for both left and right ports.

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### Logic Block Diagram



# CY7C131E, CY7C131AE CY7C136E, CY7C136AE

### Contents

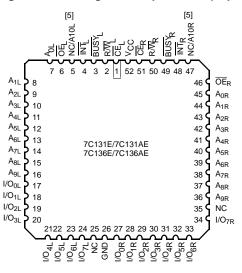
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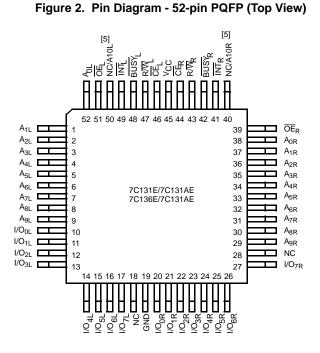
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### **Pin Configurations**

Figure 1. Pin Diagram - 52-pin PLCC (Top View)





### **Pin Definitions**

Left Port	Right Port	Description
CEL	CE <sub>R</sub>	Chip Enable
R/WL	R/W <sub>R</sub>	Read/Write Enable
OEL	OE <sub>R</sub>	Output Enable
A <sub>0L</sub> -A <sub>9/10L</sub> <sup>[5]</sup>	A <sub>0R</sub> -A <sub>9/10R</sub> <sup>[5]</sup>	Address
I/O <sub>0L</sub> -I/O <sub>7L</sub>	I/O <sub>0R</sub> -I/O <sub>7R</sub>	Data Bus Input/Output
INTL	INT <sub>R</sub>	Interrupt Flag
BUSYL	BUSY <sub>R</sub>	Busy Flag
V <sub>CC</sub>	·	Power
GND		Ground

### **Selection Guide**

Parameter	7C131E-15 7C131AE-15	7C131E-25 7C136E-25	7C131E-55 7C136E-55 7C136AE-55	Unit
Maximum Access Time	15	25	55	ns
Typical Operating Current	110	100	95	mA
Typical Standby Current for I <sub>SB1</sub> (both ports TTL level)	50	45	45	mA
Typical Standby Current for I <sub>SB3</sub> (Both ports CMOS level)	0.05	0.05	0.05	mA

Note

<sup>5. 1</sup> K x 8: A0–A9, 2 K x 8: A0–A10, address lines are for both left and right ports.



### **Maximum Ratings**

Exceeding maximum ratings <sup>[6]</sup> may shorten the useful life of the device. User guidelines are not tested.

Storage temperature65 °C to +150 °C
Ambient temperature with power applied
Supply voltage to ground potential–0.3 V to +7.0 V
DC voltage applied to outputs in High Z State0.5 V to +7.0 V

DC input voltage <sup>[8]</sup>	–0.5 V to +7.0 V
Output current into outputs (LOW)	20 mA
Static discharge voltage	>1100 V
Latch up current	>200 mA

### **Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0 °C to +70 °C	5 V ± 10%
Industrial	–40 °C to +85 °C	5 V ± 10%

### **Electrical Characteristics**

Over the Operating Range

Parameter	Description	Test Conditions			C131E-1 C131AE-	15	70	C131E-2 C136E-2		70	C131E- C136E- 136AE-	55 -55	Unit
				Min	Typ <sup>[9]</sup>	Max	Min	Typ <sup>[9]</sup>	Max	Min	Typ <sup>[9]</sup>	Max	
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC} = Min, I_{OH} = -4.0 m.$	A	2.4	Ι	-	2.4	_	—	2.4	Ι		V
V <sub>OL</sub>	Output LOW Voltage	$V_{CC}$ = Min, $I_{OL}$ = 4.0 mA		-	Ι	0.4		_	0.4	Ι	Ι	0.4	V
V <sub>IH</sub>	Input HIGH Voltage			2.2	Ι	-	2.2	_	—	2.2	Ι		V
V <sub>IL</sub>	Input LOW Voltage			_	Ι	0.8		-	0.8	-	Ι	0.8	V
I <sub>OZ</sub>	Output Leakage Current	$GND \le V_O \le V_{CC},$ Output disabled		-20	-	+20	-20	-	+20	-20	-	+20	μΑ
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max, I <sub>OUT</sub> = 0 mA Outputs disabled	Commercial Industrial	_	110 115	190 200	_	100 110	170 180	Ι	95 105	160 170	mA
I <sub>SB1</sub>	Standby Current, Both Ports, TTL Inputs	$ \begin{array}{l} CE_{L} \text{ and } CE_{R} \geq V_{IH}, \\ f = f_{MAX}^{[7]} \end{array} $	Commercial Industrial	-	50 65	70 95	-	45 65	65 95	-	45 65	65 95	mA
I <sub>SB2</sub>	Standby Current, One Port, TTL Inputs	$\begin{array}{l} CE_{L} \text{ or } CE_{R} \geq V_{IH}, \\ Active Port Outputs \\ Open, \\ f = f_{MAX}^{[7]} \end{array}$	Commercial Industrial	-	120 135	180 205	_	110 135	160 205	Ι	110 135	160 205	mA
I <sub>SB3</sub>	Standby Current, Both Ports, CMOS Inputs	$\begin{array}{l} \underline{Both} \ Ports\_\\ CE_L \ and \ CE_R \geq V_{CC} - \\ 0.2 \ V, \\ V_{IN} \geq V_{CC} - 0.2 \ V \\ or \ V_{IN} \leq 0.2 \ V, \ f = 0 \end{array}$	Commercial Industrial	_	0.05 0.05	0.5 0.5	_	0.05 0.05	0.5 0.5	-	0.05 0.05	0.5 0.5	mA
I <sub>SB4</sub>	Standby Current, One Port, CMOS Inputs	$\begin{array}{l} \underline{One} \ Port\\ \overline{CE}_L \ or \ CE_R \geq V_{CC} - 0.2\\ V,\\ V_{IN} \geq V_{CC} - 0.2 \ V\\ or \ V_{IN} \leq 0.2 \ V,\\ Active \ Port \ Outputs \ Open,\\ f = f_{MAX}^{[7]} \end{array}$	Commercial Industrial	-	110 125	160 175	-	100 125	140 175	1	100 125	140 175	mA

#### Notes

- 9. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V<sub>CC</sub> = V<sub>CC</sub>(typ.), T<sub>A</sub> = 25 °C.

<sup>6.</sup> The voltage on any I/O pin cannot exceed the power pin during power-up.

<sup>7.</sup> At  $f = f_{MAX}$ , address and data inputs are cycling at the maximum frequency of read cycle of  $1/t_{RC}$  and using AC Test Waveforms input levels of GND to 3 V. 8. Pulse width < 20 ns.

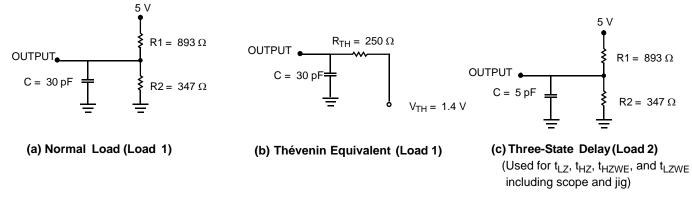


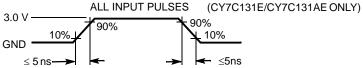
### Capacitance<sup>[10]</sup>

Parameter	Description	Test Conditions	Max	Unit
C <sub>IN</sub>	Input capacitance	$T_A = 25 \text{ °C}, f = 1 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	15	pF
C <sub>OUT</sub>	Output capacitance		10	pF

### AC Test Loads and Waveforms

Figure 3. AC Test Loads and Waveforms







### **Switching Characteristics**

Over the Operating Range

Parameter [11]	Description	7C131E-15/	7C131AE-15	7C131E-25/7C136E-25		Unit
Parameter		Min	Max	Min	Max	Unit
Read Cycle	•					
t <sub>RC</sub>	Read cycle time	15	-	25	-	ns
t <sub>AA</sub>	Address to data valid <sup>[12]</sup>	-	15	_	25	ns
t <sub>OHA</sub>	Data hold from Address change	3	-	3	-	ns
t <sub>ACE</sub>	CE LOW to data valid <sup>[12]</sup>	-	15	-	25	ns
t <sub>DOE</sub>	OE LOW to data valid <sup>[12]</sup>	-	10	_	15	ns
t <sub>LZOE</sub>	OE LOW to Low Z [13, 14, 15]	3	-	3	-	ns
t <sub>HZOE</sub>	OE HIGH to High Z <sup>[13, 14, 15]</sup>	-	10	_	15	ns
t <sub>LZCE</sub>	CE LOW to Low Z [13, 14, 15]	3	-	5	-	ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[13, 14, 15]</sup>	-	10	_	15	ns
t <sub>PU</sub>	CE LOW to power-up <sup>[13]</sup>	0	-	0	-	ns
t <sub>PD</sub>	CE HIGH to power-down [13]	-	15	_	25	ns
Write Cycle [16]	•					
t <sub>WC</sub>	Write cycle time	15	-	25	-	ns
t <sub>SCE</sub>	CE LOW to write end	12	-	20	-	ns
t <sub>AW</sub>	Address setup to write end	12	-	20	-	ns
t <sub>HA</sub>	Address hold from write end	0	-	0	-	ns
t <sub>SA</sub>	Address setup to write start	0	-	0	-	ns
t <sub>PWE</sub>	$R/\overline{W}$ pulse width	10	-	12	-	ns
t <sub>SD</sub>	Data setup to write end	10	-	15	-	ns
t <sub>HD</sub>	Data hold from write end	0	-	0	-	ns
t <sub>HZWE</sub> <sup>[13]</sup>	$R/\overline{W}$ LOW to High Z <sup>[15]</sup>	_	10	_	15	ns
t <sub>LZWE</sub> <sup>[13]</sup>	$R/\overline{W}$ HIGH to Low Z <sup>[15]</sup>	3	-	3	-	ns

- Notes
  11. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub>, and 30 pF load capacitance.
  12. AC Test Conditions use V<sub>OH</sub> = 1.6 V and V<sub>OL</sub> = 1.4 V.
  13. This parameter is guaranteed but not tested.
  14. At any given temperature and voltage condition for any given device, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> and t<sub>HZOE</sub> is less than t<sub>LZOE</sub>.
  15. Parameters t<sub>LZCE</sub>, t<sub>LZWE</sub>, t<sub>HZOE</sub>, t<sub>LZOE</sub>, t<sub>HZCE</sub> and t<sub>HZWE</sub> are tested with C<sub>L</sub> = 5 pF as in part (c) of Figure 3 on page 5. Transition is measured ±500 mV from steady state voltage.
  16. The internal write time of the memory is defined by the overlap of CE LOW and R/W LOW. Both signals must be low to initiate a write and either signal can terminate



### Switching Characteristics (continued)

Over the Operating Range

Parameter [11]	Description	7C131E-15	/7C131AE-15	7C131E-25/7C136E-25		Unit
Farameter	Description	Min	Max	Min	Max	Unit
Busy/Interrupt 1	fiming <sup>[17]</sup>		•		·	
t <sub>BLA</sub>	BUSY LOW from Address match	-	15	-	20	ns
t <sub>BHA</sub>	BUSY HIGH from Address mismatch <sup>[18]</sup>	-	15	-	20	ns
t <sub>BLC</sub>	BUSY LOW from CE LOW	-	15	-	20	ns
t <sub>BHC</sub>	BUSY HIGH from CE HIGH [18]	-	15	-	20	ns
t <sub>PS</sub>	Port setup for priority	5	-	5	-	ns
t <sub>BDD</sub>	BUSY HIGH to valid data	-	15	-	25	ns
t <sub>DDD</sub>	Write data valid to read data valid <sup>[19]</sup>	-	25	-	30	ns
t <sub>WDD</sub>	Write pulse to data delay <sup>[19]</sup>	-	30	-	45	ns
Interrupt Timing	1					
t <sub>WINS</sub>	R/W to INTERRUPT set time	-	15	-	25	ns
t <sub>EINS</sub>	CE to INTERRUPT set time	-	15	-	25	ns
t <sub>INS</sub>	Address to INTERRUPT set time	-	15	-	25	ns
t <sub>OINR</sub>	OE to INTERRUPT reset time [18]	-	15	-	25	ns
t <sub>EINR</sub>	CE to INTERRUPT reset time [18]	-	15	-	25	ns
t <sub>INR</sub>	Address to INTERRUPT reset time [18]	_	15	_	25	ns

Notes

17. Test conditions used are Load 2.

18. These conditions used are Load 2.
18. These parameters are measured from the input signal changing, until the output pin goes to a high impedance state.
19. <u>A write</u> operation on Port A, where Port A has priority, leaves the data on Port B's outputs undisturbed until one access time after one of the following: BUSY on Port B goes HIGH.
<u>Port</u> B's address toggled.
CE for Port B is toggled.



### **Switching Characteristics**

Over the Operating Range

Parameter	Description	7C131 7C136 7C136	6E-55	Unit
		Min	Max	
Read Cycle				
t <sub>RC</sub>	Read cycle time	55	_	ns
t <sub>AA</sub>	Address to data valid <sup>[21]</sup>	-	55	ns
t <sub>OHA</sub>	Data hold from Address change	3	_	ns
t <sub>ACE</sub>	CE LOW to data valid <sup>[21]</sup>	-	55	ns
t <sub>DOE</sub>	OE LOW to data valid <sup>[21]</sup>	-	25	ns
t <sub>LZOE</sub>	OE LOW to Low Z <sup>[21, 22, 23]</sup>	3	_	ns
t <sub>HZOE</sub>	OE HIGH to High Z [21, 22, 23]	-	25	ns
t <sub>LZCE</sub>	CE LOW to Low Z [21, 22, 23]	5	_	ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[21, 22, 23]</sup>	_	25	ns
t <sub>PU</sub>	CE LOW to power-up <sup>[22]</sup>	0	_	ns
t <sub>PD</sub>	CE HIGH to power-down <sup>[22]</sup>	_	35	ns
Write Cycle				
t <sub>WC</sub>	Write cycle time	55	-	ns
t <sub>SCE</sub>	CE LOW to write end	40	_	ns
t <sub>AW</sub>	Address setup to write end	40	_	ns
t <sub>HA</sub>	Address hold from write end	2	_	ns
t <sub>SA</sub>	Address setup to write start	0	_	ns
t <sub>PWE</sub>	R/W pulse width	30	_	ns
t <sub>SD</sub>	Data setup to write end	20	_	ns
t <sub>HD</sub>	Data hold from write end	0	_	ns
t <sub>HZWE</sub>	$R/\overline{W}$ LOW to High Z <sup>[24]</sup>	_	25	ns
t <sub>LZWE</sub>	$R/\overline{W}$ HIGH to Low Z <sup>[24]</sup>	3	_	ns
Busy/Interru	pt Timing <sup>[20]</sup>			
t <sub>BLA</sub>	BUSY LOW from Address match	_	30	ns
t <sub>BHA</sub>	BUSY HIGH from Address mismatch <sup>[25]</sup>		30	ns
t <sub>BLC</sub>	BUSY LOW from CE LOW	_	30	ns
t <sub>BHC</sub>	BUSY HIGH from CE HIGH [25]	_	30	ns
t <sub>PS</sub>	Port setup for priority	5	-	ns
t <sub>BDD</sub>	BUSY HIGH to valid data	_	45	ns

Notes

20. Test conditions used are Load 2.

21. The internal write time of the memory is defined by the overlap of CE LOW and R/W LOW. Both signals must be low to initiate a write and either signal can terminate a write by going high. The data input setup and hold timing should be referenced to the rising edge of the signal that terminates the write.

22. AC Test Conditions use  $V_{OH} = 1.6$  V and  $V_{OL} = 1.4$  V. 23. These parameters are measured from the input signal changing, until the output pin goes to a high impedance state. 24. Parameters  $t_{LZCE}$ ,  $t_{LZWE}$ ,  $t_{HZOE}$ ,  $t_{HZOE}$ ,  $t_{HZCE}$  and  $t_{HZWE}$  are tested with C = 5 pF as in part (b) of Figure 3 on page 5. Transition is measured ±500 mV from steady state voltage state voltage.

25. <u>A write</u> operation on Port A, where Port A has priority, leaves the data on Port B's outputs undisturbed until one access time after one of the following: BUSY on Port B goes HIGH. Port B's address toggled.



### **Switching Characteristics (continued)**

### Over the Operating Range

Parameter	Description	7C131E-55 7C136E-55 7C136AE-55		Unit
		Min	Max	
t <sub>DDD</sub>	Write data valid to read data valid <sup>[26]</sup>	-	30	ns
t <sub>WDD</sub>	Write pulse to data delay <sup>[26]</sup>	-	45	ns
Interrupt Timi	ing	•		
t <sub>WINS</sub>	R/W to INTERRUPT set time	-	45	ns
t <sub>EINS</sub>	CE to INTERRUPT set time	-	45	ns
t <sub>INS</sub>	Address to INTERRUPT set time	-	45	ns
t <sub>OINR</sub>	OE to INTERRUPT reset time <sup>[27]</sup>	-	45	ns
t <sub>EINR</sub>	CE to INTERRUPT reset time <sup>[27]</sup>	-	45	ns
t <sub>INR</sub>	Address to INTERRUPT reset time <sup>[27]</sup>		45	ns

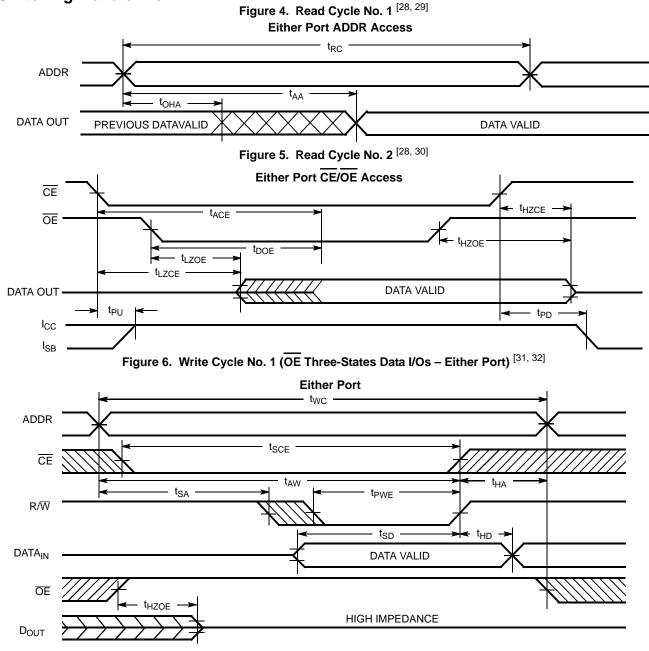
Notes

26. A write operation on Port A, where Port A has priority, leaves the data on Port B's outputs undisturbed until one access time after one of the following: BUSY on Port B goes HIGH. Port B's address toggled. CE for Port B is toggled during valid read. 27. The port B is toggled during valid read.

27. These parameters are measured from the input signal changing, until the output pin goes to a high impedance state.



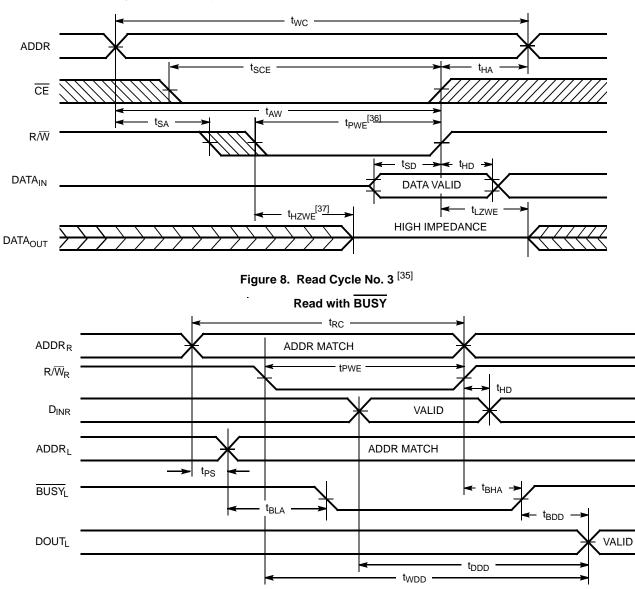
### **Switching Waveforms**



#### Notes

- 28. R/W is HIGH for read cycle.
- 29. Device is continuously selected,  $\overline{CE} = V_{IL}$  and  $\overline{OE} = V_{IL}$ . 30. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.
- 31. The internal write time of the memory is defined by the overlap of CE LOW and RW LOW. Both signals must be LOW to initiate a write and either signal can
- terminate a write by going HIGH. The data input setup and hold timing must be referenced to the rising edge of the signal that terminates the write.
   If OE is LOW during a R/W controlled write cycle, the write pulse width must be the larger of t<sub>PWE</sub> or t<sub>HZWE</sub> + t<sub>SD</sub> to allow the data I/O pins to enter high impedance and for data to be placed on the bus for the required t<sub>SD</sub>.





Switching Waveforms (continued) Figure 7. Write Cycle No. 2 (R/W Three-States Data I/Os – Either Port) <sup>[33, 34]</sup>

#### Notes

33. These parameters are measured from the input signal changing, until the output pin goes to a high impedance state.

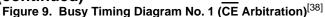
- 34. If the CE LOW transition occurs simultaneously with or after the R/W LOW transition, the outputs remain in a high impedance state.
- 35.  $\overline{CEL} = \overline{CER} = LOW.$

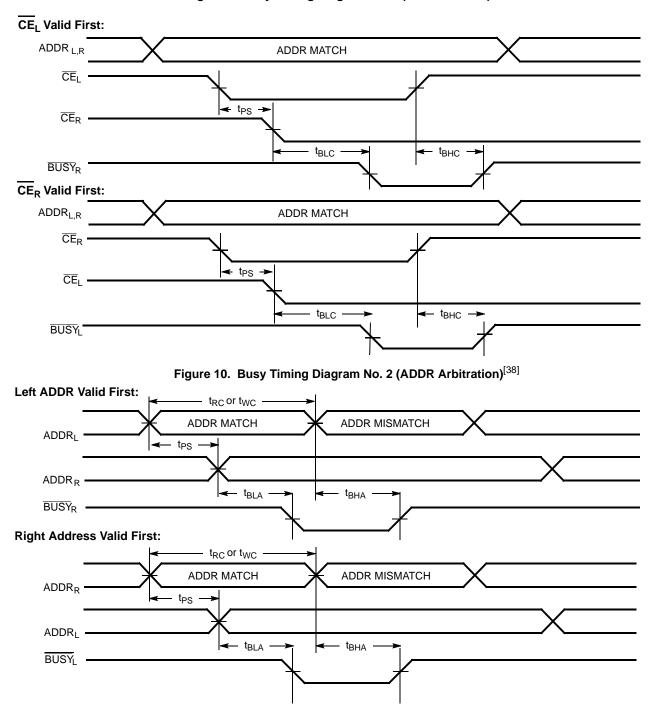
36. If OE is LOW during a R/W controlled write cycle, the write pulse width must be the larger of tPWE or (tHZWE + tSD) to allow the I/O drivers to turn off and data to be placed on the bus for the required tSD. If OE is HIGH during a R/Wn controlled write cycle, this requirements does not apply and the write pulse can be as short as the specified tPWE.

37. Transition is measured ±500 mV from steady state with a 5 pF load (including scope and jig). This parameter is sampled and not 100% tested.



### Switching Waveforms (continued)



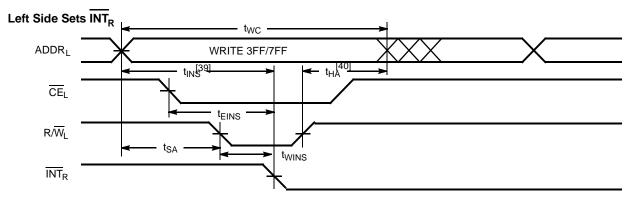


#### Note

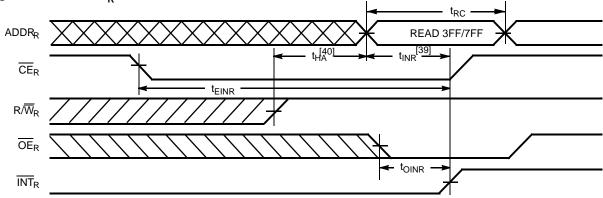
38. If tPS is violated, the busy signal will be asserted on one side or the other, but there is no guarantee to which side BUSY will be asserted.



### **Switching Waveforms (continued)** Figure 11. Interrupt Timing Diagrams



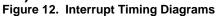
Right Side Clears INT<sub>R</sub>

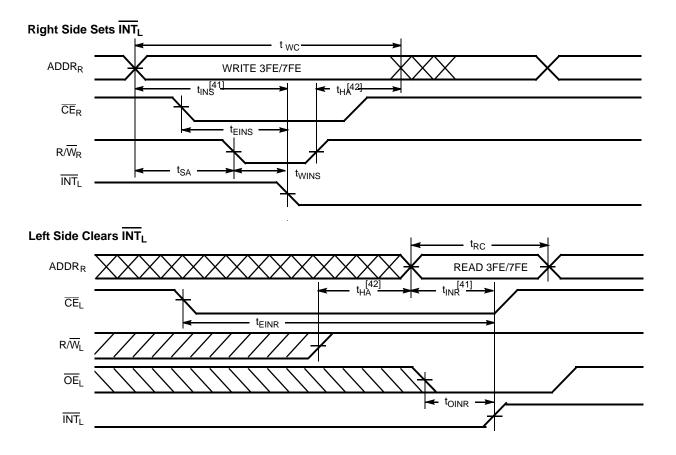


**Notes** 39. Parameter  $t_{INS}$  or  $t_{INR}$  depends on which  $enable pin (\overline{CE}_L \text{ or } R/\overline{W}_L)$  is asserted last. 40. Parameter  $t_{HA}$  depends on which enable pin ( $\overline{CE}_L$  or  $R/W_L$ ) is deasserted first.



### **Switching Waveforms (continued)**





Notes

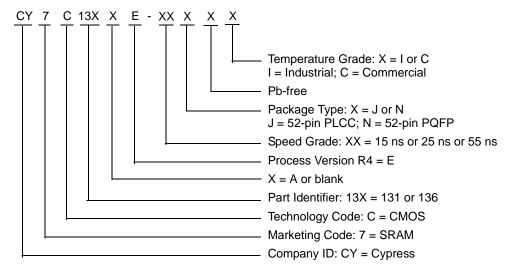
41. Parameter  $t_{INS}$  or  $t_{INR}$  depends on which enable pin ( $\overline{CE}_L$  or  $R/\overline{W}_L$ ) is asserted last. 42. Parameter  $t_{HA}$  depends on which enable pin ( $\overline{CE}_L$  or  $R/W_L$ ) is deasserted first.



### **Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
1 K × 8	Dual-port SRAM	·	·	·
15	CY7C131AE-15JXI	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Industrial
	CY7C131E-15NXI	51-85042	52-pin Pb-free Plastic Quad Flatpack	
25	CY7C131E-25JXC	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Commercial
	CY7C131E-25NXC	51-85042	52-pin Pb-free Plastic Quad Flatpack	
55	CY7C131E-55JXC	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Commercial
	CY7C131E-55NXC	51-85042	52-pin Pb-free Plastic Quad Flatpack	
	CY7C131E-55JXI	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Industrial
	CY7C131E-55NXI	51-85042	52-pin Pb-free Plastic Quad Flatpack	
2 K × 8	Dual-port SRAM	•		
25	CY7C136E-25JXC	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Commercial
	CY7C136E-25NXC	51-85042	52-pin Pb-free Plastic Quad Flatpack	
	CY7C136E-25JXI	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Industrial
55	CY7C136E-55JXC	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Commercial
	CY7C136E-55NXC	51-85042	52-pin Pb-free Plastic Quad Flatpack	
	CY7C136AE-55JXI	51-85004	52-pin Pb-free Plastic Leaded Chip Carrier	Industrial
	CY7C136AE-55NXI	51-85042	52-pin Pb-free Plastic Quad Flatpack	7

### **Ordering Code Definitions**





### **Package Diagrams**

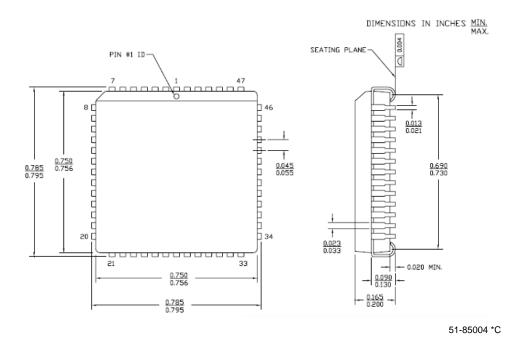
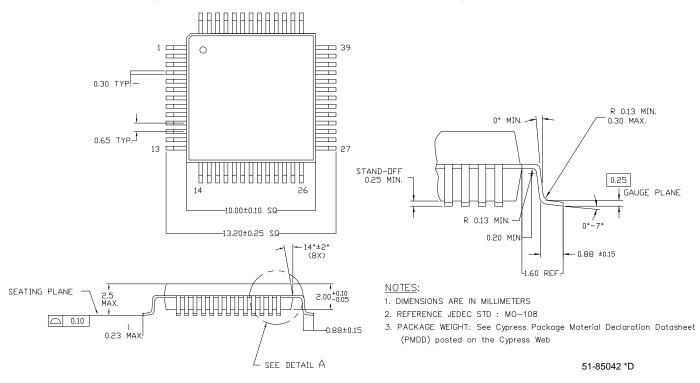


Figure 13. 52-pin PLCC (0.756 × 0.756 Inches) J52 Package Outline, 51-85004

Figure 14. 52-pin PQFP (10 × 10 × 2.0 mm) N5210 Package Outline, 51-85042





### Acronyms

Acronym	Description
CE	chip enable
CMOS	complementary metal oxide semiconductor
I/O	input/output
OE	output enable
PLCC	plastic leaded chip carrier
PQFP	plastic quad flat package
SRAM	static random access memory
TTL	transistor-transistor logic
WE	write enable

### **Document Conventions**

### Units of Measure

Symbol	Unit of Measure	
°C	degree Celsius	
μA	microampere	
mA	milliampere	
mV	millivolt	
ns	nanosecond	
Ω	ohm	
%	percent	
pF	picofarad	
V	volt	
W	watt	



### **Document History Page**

Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	3038037	ADMU	09/24/2010	New data sheet
*A	3394800	ADMU	10/04/2011	Changed status from Preliminary to Final. Updated Maximum Ratings (Removed (Pin 48 to Pin 24)). Updated Electrical Characteristics (changed minimum value of $I_{OZ}$ parameter from -10 µA to -20 µA, changed maximum value of $I_{OZ}$ parameter from +10 µA to +20 µA and changed maximum value of $I_{SB3}$ from 0.5 mA to 15 m/ for both Commercial and Industrial temperature ranges). Updated Package Diagrams (Updated revision of 51-85004 from *B to *C an revision of 51-85042 from *A to *C). Updated in new template.
*B	3403147	ADMU	10/12/2011	No technical updates.
*C	3435230	ADMU	11/17/2011	Updated Features (Removed a feature "Expandable data bus width to 16 bit or more using Master/Slave chip select <u>when</u> using more than one device and updated another feature to read as "BUSY output flag to indicate access to the same location by both ports.". Updated Functional Description (Updated the sentence in the first paragrap to read as "The CY7C131E / CY7C131AE / CY7C136E / CY7C136AE can b used as a standalone dual-p <u>ort stat</u> tic RAM.". Updated Note 2 to read as "BUSY is a push-pull output. No pull-up resistor required.". Updated Note 3 to read as "Interrupt: push-pull output. No pull-up resistor required.". Updated Maximum Ratings (Removed "(per MIL-STD-883, Method 3015)") Updated Electrical Characteristics (Removed the Note "See the last page of this specification for Group A subgroup testing information." and its reference in Parameter column.). Updated AC Test Loads and Waveforms. Updated AC Test Loads and Waveforms. Updated Switching Characteristics (Removed the Note "See the last page of this specification for Group A subgroup testing information." and its reference in Parameter column.). Updated AC Test Loads and Waveforms. Updated Switching Characteristics (Removed the Note "See the last page of this specification for Group A subgroup testing information." and its reference in Parameter column.). Updated Switching Characteristics (Removed the Note "See the last page of this specification for Group A subgroup testing information." and its reference in Parameter column.). Updated Switching Characteristics (Changed the minimum value of t <sub>OHA</sub> from 0 ns to 3 ns). Removed the section "Typical DC and AC Characteristics". Removed the section "Reference Documents".
*D	3620277	ADMU	06/15/2012	Added footnotes 9, 13, 17, 20, 36, 37, 39, 40, 41, and 42. Missing overbars updated. Removed "Slave Diagrams". Updated Figure 3 with value 5 ns. Updated Maximum Ratings (updated Static discharge voltage from 2001 V to 1100 V). Corrected the typo in Electrical Characteristics. Updated Package Diagrams (51-85042 from Rev *C to *D). Updated I <sub>CC</sub> parameters in Electrical Characteristics table. Updated Typical Operating Current parameters in Selection Guide.



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